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(54) Title: ELECTROLESS NICKEL PLATING SOLUTION

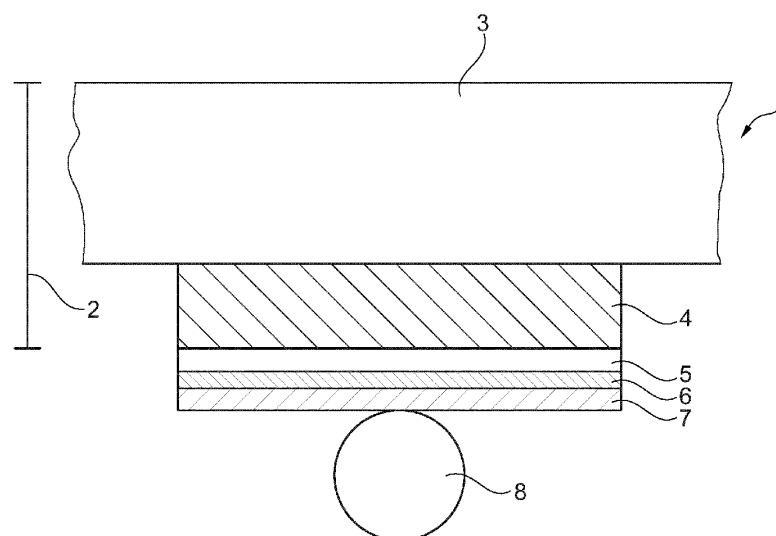


Fig. 1

(57) Abstract: An electroless nickel plating solution, comprising - a source of nickel ions, - a source of molybdenum ions, - a source of tungsten ions, - a source of hypophosphite ions - at least one complexing agent, - at least one organic sulphur containing compound in a concentration of 0.38 – 38.00 µmol/L, and - at least one amino acid in a concentration of 0.67 – 40.13 mmol/L, a method for electroless plating of a nickel alloy layer on a substrate, a nickel alloy layer and an article comprising the a nickel alloy layer.

[Continued on next page]



WO 2020/094642 A1

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